

# Power manegement (dual transistors)

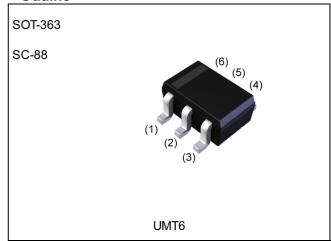
### <For Tr1>

Parameter	Value
V <sub>CEO</sub>	-50V
I <sub>C</sub>	-150mA

### <For DTr2>

Parameter	Value
V <sub>CC</sub>	50V
I <sub>C(Max.)</sub>	100mA

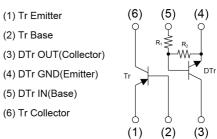
### Outline



### Features

- 1)Power switching circuit (2SA1576A/DTC124XUA) in a single package.
- 2) Mounting cost and area can be cut in half.

### •Inner circuit



# Application

Power manegement

### Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
UMF28N	SOT-363 (UMT6)	2021	TR	180	8	3000	F28

# ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

# <Tr1>

Parameter	Symbol	Limits	Unit
Collector-base voltage	V <sub>CBO</sub>	-60	V
Collector-emitter voltage	$V_{CEO}$	-50	V
Emitter-base voltage	V <sub>EBO</sub>	-6	V
Collector current	I <sub>C</sub>	-150	mA

### <DTr2>

Parameter	Symbol	Limits	Unit
Supply voltage	V <sub>CC</sub>	50	V
Input voltage	V <sub>IN</sub>	-10 to 40	V
Output current	Io	50	mA
Collector current	I <sub>C(MAX)</sub> *2	100	mA

# <Tr1> <DTr2>

Parameter	Symbol	Limits	Unit
Power dissipation	P <sub>D</sub> *1*3	150	mW
Junction temperature	T <sub>j</sub>	150	°C
Range of storage temperature	T <sub>stg</sub>	-55 to 150	°C

# ● Electrical characteristics (T<sub>a</sub> = 25°C) <For Tr1>

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Collector-base breakdown voltage	$BV_CBO$	I <sub>C</sub> = -50μA	-60	1	-	V
Collector-emitter breakdown voltage	$BV_CEO$	I <sub>C</sub> = -1mA	-50	-	-	V
Emitter-base breakdown voltage	$BV_{EBO}$	I <sub>E</sub> = -50μA	-6	-	-	V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = -60V	-	-	-100	nA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = -6V	-	-	-100	nA
Collector-emitter saturation voltage	$V_{CE(sat)}$	I <sub>C</sub> = -50mA, I <sub>B</sub> = -5mA	-	-	-500	mV
DC current gain	h <sub>FE</sub>	$V_{CE} = -6V, I_{C} = -1mA$	180	-	390	-
Transition frequency	f <sub>T</sub>	V <sub>CE</sub> = -12V, I <sub>E</sub> = 2mA, f = 100MHz	-	140	-	MHz
Output capacitance	$C_ob$	V <sub>CB</sub> = -12V, I <sub>E</sub> = 0mA, f = 1MHz	-	4.0	5.0	pF

# ● Electrical characteristics (Ta = 25°C) <For DTr2>

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
land to the me	$V_{l(off)}$	$V_{CC} = 5V$ , $I_{O} = 100 \mu A$	-	-	0.4	V
Input voltage	V <sub>I(on)</sub>	V <sub>O</sub> = 0.3V, I <sub>O</sub> = 2mA	2.5	-	-	V
Output voltage	V <sub>O(on)</sub>	I <sub>O</sub> / I <sub>I</sub> = 10mA / 0.5mA	-	100	300	mV
Input current	I <sub>1</sub>	V <sub>I</sub> = 5V	-	-	360	μA
Output current	I <sub>O(off)</sub>	V <sub>CC</sub> = 50V, VI = 0V	-	-	500	nA
DC current gain	G <sub>l</sub>	V <sub>O</sub> = 5V, I <sub>O</sub> = 5mA	68	-	-	-
Input resistance	R <sub>1</sub>	-	15.4	22	28.6	kΩ
Resistance ratio	R <sub>2</sub> /R <sub>1</sub>	-	1.7	2.1	2.6	-
Transition frequency	f <sub>T</sub> *2	V <sub>CE</sub> = 10V, I <sub>E</sub> = -5mA, f = 100MHz		250	-	MHz

<sup>\*1</sup> Each termunal mounted on a reference land.

<sup>\*2</sup> Characteristics of built-in transistor.

<sup>\*3 120</sup>mW per element must not be exceeded.

# ● Electrical characteristic curves(T<sub>a</sub>=25°C) <For Tr1>

Fig.1 Grounded emitter propagation characteristics

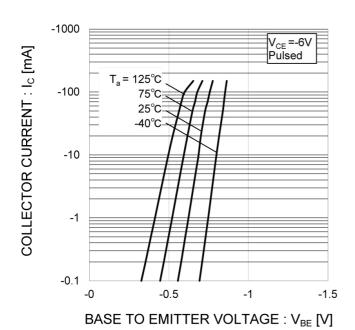
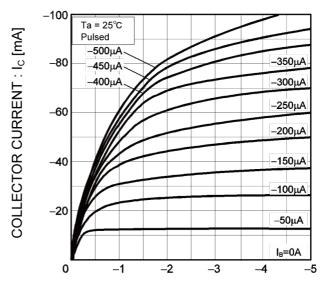


Fig.2 Grounded emitter output characteristics



COLLECTOR TO EMITTER VOLTAGE: V<sub>CE</sub> [V]

Fig.3 DC current gain vs. collector current (I)

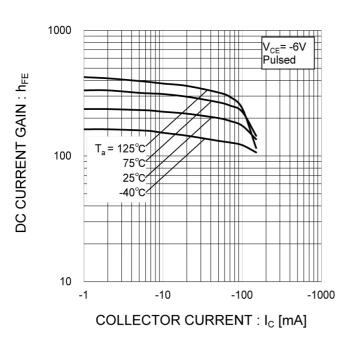
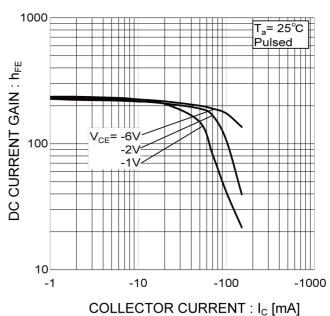


Fig.4 DC current gain vs. collector current (II)



# ● Electrical characteristic curves(T<sub>a</sub>=25°C) <For Tr1>

Fig.5 Collector- emitter saturation voltage vs. collector current (I)

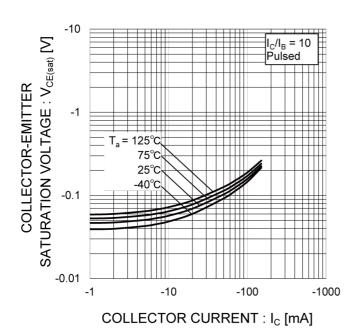
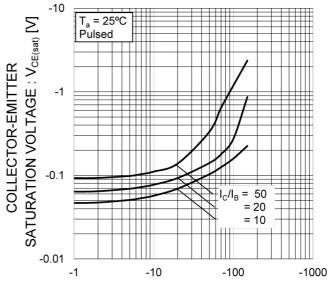


Fig.6 Collector- emitter saturation voltage vs. collector current (II)



COLLECTOR CURRENT : I<sub>C</sub> [mA]

Fig.7 Base- emitter saturation voltage vs. collector current

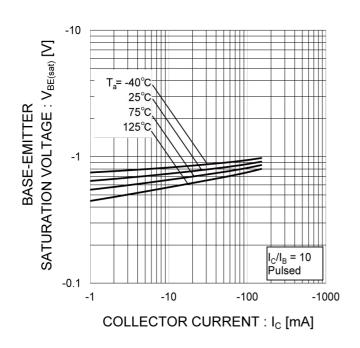
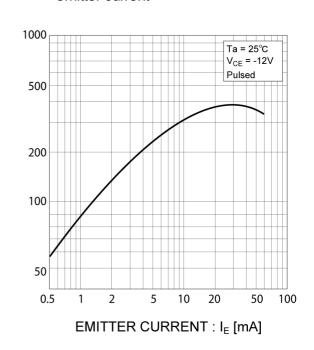


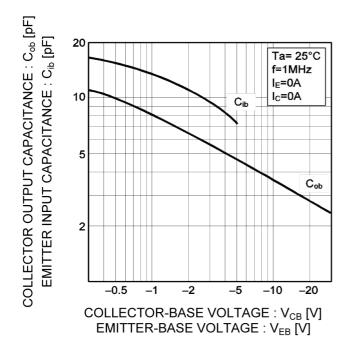
Fig.8 Gain bandwidth product vs. emitter current



TRANSITION FREQUENCY : fr [MHz]

# ● Electrical characteristic curves(T<sub>a</sub>=25°C) <For Tr1>

Fig.9 Emitter Input Capacitance vs.
Emitter-Base Voltage
Collector Output Capacitance vs.
Collector-Base Voltage





# ● Electrical characteristic curves(T<sub>a</sub>=25°C) < For DTr2>

Fig.1 Input Voltage vs. Output Current (ON Characteristics)

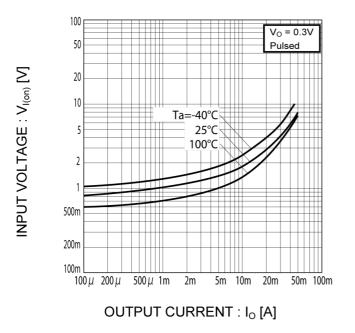


Fig.2 Output Current vs. Input Voltage (OFF Characteristics)

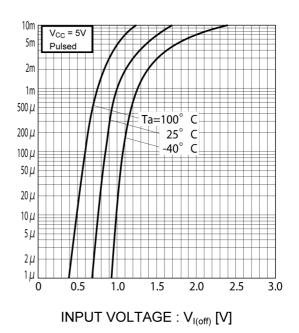


Fig.3 Output Current vs. Output Voltage

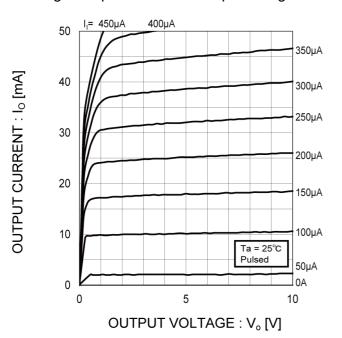
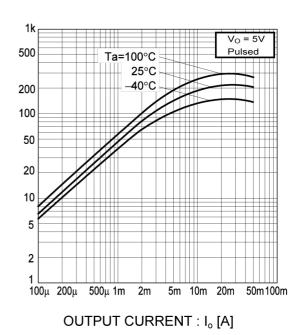


Fig.4 DC Current Gain vs. Output Current

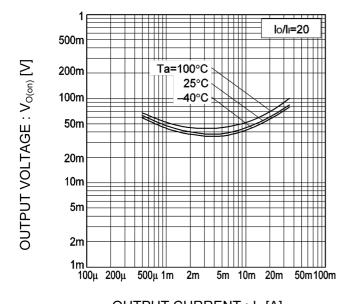


DC CURRENT GAIN: G

OUTPUT CURRENT : Io [A]

# ● Electrical characteristic curves(T<sub>a</sub>=25°C) < For DTr2>

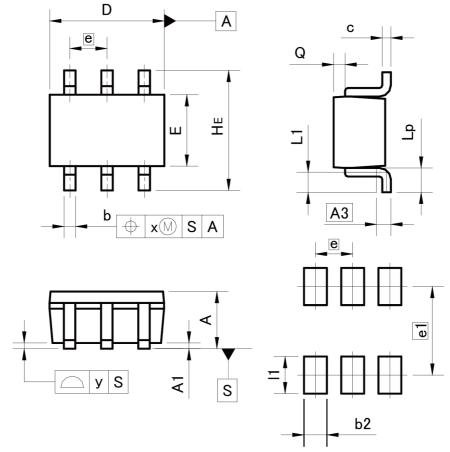
Fig.5 Output Voltage vs. Output Current



OUTPUT CURRENT :  $I_{\circ}$  [A]

# Dimensions

UMT6



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	0.80	1.00	0.031	0.039	
A1	0.00	0.10	0.000	0.004	
A3	0.3	25	0.0	10	
b	0.15	0.30	0.006	0.012	
С	0.10	0.20	0.004	0.008	
D	1.90	2.10	0.075	0.083	
E	1.15	1.35	0.045	0.053	
е	0.0	65	0.026		
HE	2.00	2.20	0.079	0.087	
L1	0.20	0.50	0.008	0.020	
Lp	0.25	0.55	0.010	0.022	
Q	0.10	0.30	0.004	0.012	
х	_	0.10	_	0.004	
У	_	0.10	_	0.004	

	DIM	MILIMETERS		INCHES	
DIM		MIN	MAX	MIN	MAX
	b2	-	0.40	1	0.016
	e1	1.	55	0.0	61
	<b>I</b> 1	- 0.65		ı	0.026

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CI ACCIII	CLASS II b	CI VCCIII
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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